IGBT - Short-Circuit Rated

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Non–Punch Through (NPT) Trench construction, and provides superior performance in demanding switching applications. Offering both low on state voltage and minimal switching loss, the IGBT is well suited for motor drive control and other hard switching applications. Incorporated into the device is a rugged co–packaged reverse recovery diode with a low forward voltage.

Features

- Low Saturation Voltage Resulting in Low Conduction Loss
- Low Switching Loss in Higher Frequency Applications
- Soft Fast Reverse Recovery Diode
- 10 us Short Circuit Capability
- Excellent Current versus Package Size Performance Density
- This is a Pb–Free Device

Typical Applications

- White Goods Appliance Motor Control
- General Purpose Inverter
- AC and DC Motor Control

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage	V _{CES}	600	V
Collector current @ Tc = 25°C @ Tc = 100°C	Ι _C	30 15	Α
Pulsed collector current, T _{pulse} limited by T _{Jmax}	I _{CM}	120	Α
Diode forward current @ Tc = 25°C @ Tc = 100°C	lF	30 15	Α
Diode pulsed current, T _{pulse} limited by T _{Jmax}	I _{FM}	120	А
Gate-emitter voltage	$V_{\sf GE}$	±20	V
Power dissipation @ Tc = 25°C @ Tc = 100°C	P _D	117 47	W
Short circuit withstand time V_{GE} = 15 V, V_{CE} = 400 V, T_{J} \leq +150°C	t _{SC}	10	μS
Operating junction temperature range	TJ	-55 to +150	°C
Storage temperature range	T _{stg}	-55 to +150	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T _{SLD}	260	°C

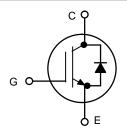
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

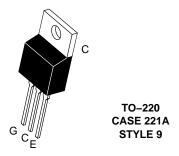


ON Semiconductor®

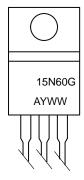
www.onsemi.com

15 A, 600 V V_{CEsat} = 1.7 V





MARKING DIAGRAM



A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGTB15N60EG	TO-220 (Pb-Free)	50 Units / Rail

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction to case, for IGBT	$R_{ heta JC}$	1.06	°C/W
Thermal resistance junction to case, for Diode	$R_{ heta JC}$	3.76	°C/W
Thermal resistance junction to ambient	$R_{ heta JA}$	60	°C/W

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

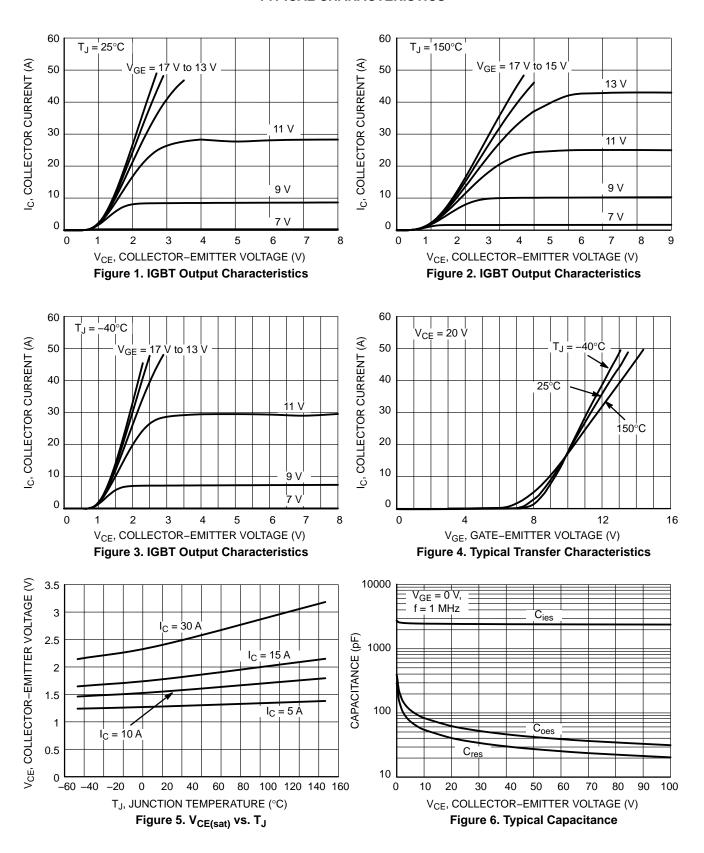
Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC						
Collector–emitter breakdown voltage, gate–emitter short–circuited	V_{GE} = 0 V, I_C = 500 μA	V _{(BR)CES}	600	-	-	V
Collector-emitter saturation voltage	V _{GE} = 15 V , I _C = 15 A V _{GE} = 15 V , I _C = 15 A, T _J = 150°C	V _{CEsat}	1.45 1.8	1.7 2.1	1.95 2.4	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}$, $I_C = 250 \mu A$	V _{GE(th)}	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate-emitter short-circuited	V _{GE} = 0 V, V _{CE} = 600 V V _{GE} = 0 V, V _{CE} = 600 V, T _J = 150°C	I _{CES}	- -	10 -	_ 200	μΑ
Gate leakage current, collector–emitter short–circuited	$V_{GE} = 20 \text{ V}, V_{CE} = 0 \text{ V}$	I _{GES}	-	-	100	nA
Forward Transconductance	V _{CE} = 20 V, I _C = 15 A	9fs	_	10.1	-	S
DYNAMIC CHARACTERISTIC						
Input capacitance		C _{ies}	_	2600	-	
Output capacitance	$V_{CE} = 20 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$	C _{oes}	_	64	-	pF
Reverse transfer capacitance		C _{res}	_	42	_	
Gate charge total		Qg	_	80	-	nC
Gate to emitter charge	$V_{CE} = 480 \text{ V}, I_{C} = 15 \text{ A}, V_{GE} = 15 \text{ V}$	Q _{ge}	_	24	-	
Gate to collector charge		Q_{gc}	_	33	-	
SWITCHING CHARACTERISTIC , INDUCTIVE	LOAD					
Turn-on delay time		t _{d(on)}	-	78	-	ns
Rise time		t _r	-	30	-	
Turn-off delay time	T _J = 25°C	t _{d(off)}	-	130	-	
Fall time	$V_{CC} = 400 \text{ V}, I_{C} = 15 \text{ A}$ $R_{c} = 22 \Omega$	t _f	-	120	_	
Turn-on switching loss	$R_g = 22 \Omega$ $V_{GE} = 0 V / 15 V$	E _{on}	-	0.900	-	
Turn-off switching loss		E _{off}	_	0.300	-	mJ
Total switching loss		E _{ts}	-	1.200	-	
Turn-on delay time		t _{d(on)}	-	76	_	
Rise time		t _r	-	33	_	20
Turn-off delay time	T _J = 150°C	t _{d(off)}	-	133	_	ns
Fall time	$V_{CC} = 400 \text{ V}, I_{C} = 15 \text{ A}$ $R_{g} = 22 \Omega$	t _f	-	223	_	
Turn-on switching loss	$V_{GE} = 0 \text{ V} / 15 \text{ V}$	E _{on}	-	1.10	_	
Turn-off switching loss		E _{off}	-	0.510	_	mJ
Total switching loss		E _{ts}	-	1.610	-	
DIODE CHARACTERISTIC						
Forward voltage	V _{GE} = 0 V, I _F = 15 A V _{GE} = 0 V, I _F = 15 A, T _J = 150°C	V _F	_ _	1.6 1.6	1.85 -	V

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
DIODE CHARACTERISTIC						
Reverse recovery time	T _J = 25°C	t _{rr}	-	270	_	ns
Reverse recovery charge	$I_F = 15 \text{ A}, V_R = 200 \text{ V}$ $di_F/dt = 200 \text{ A/}\mu\text{s}$	Q _{rr}	-	350	-	nc
Reverse recovery current		I _{rrm}	-	5	-	Α
Reverse recovery time	T _J = 125°C	t _{rr}	-	350	-	ns
Reverse recovery charge	$I_F = 15 \text{ A}, V_R = 200 \text{ V}$ $di_F/dt = 200 \text{ A/}\mu\text{s}$	Q _{rr}	-	1000	-	nc
Reverse recovery current		I _{rrm}	-	7.5	-	Α

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

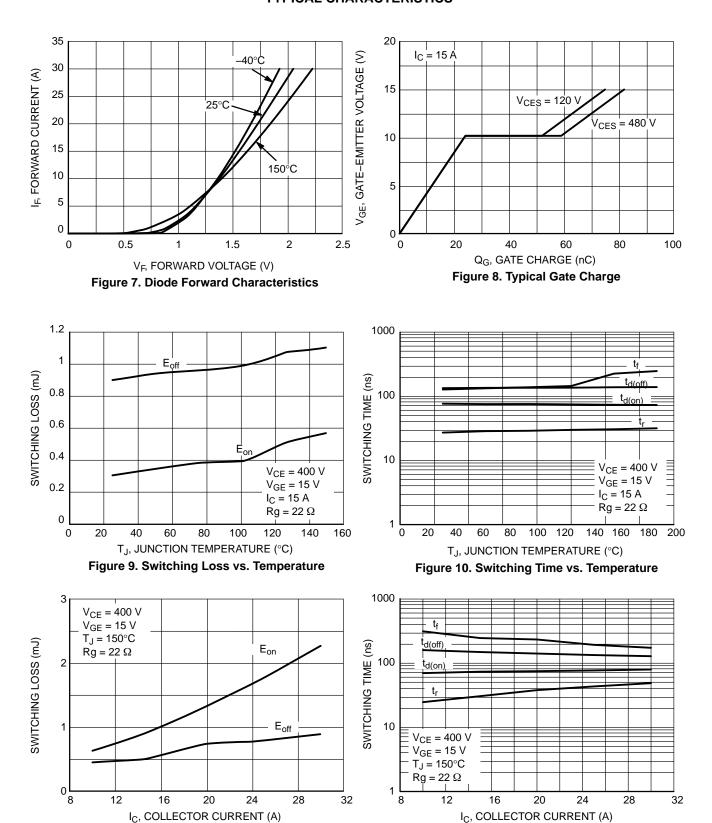
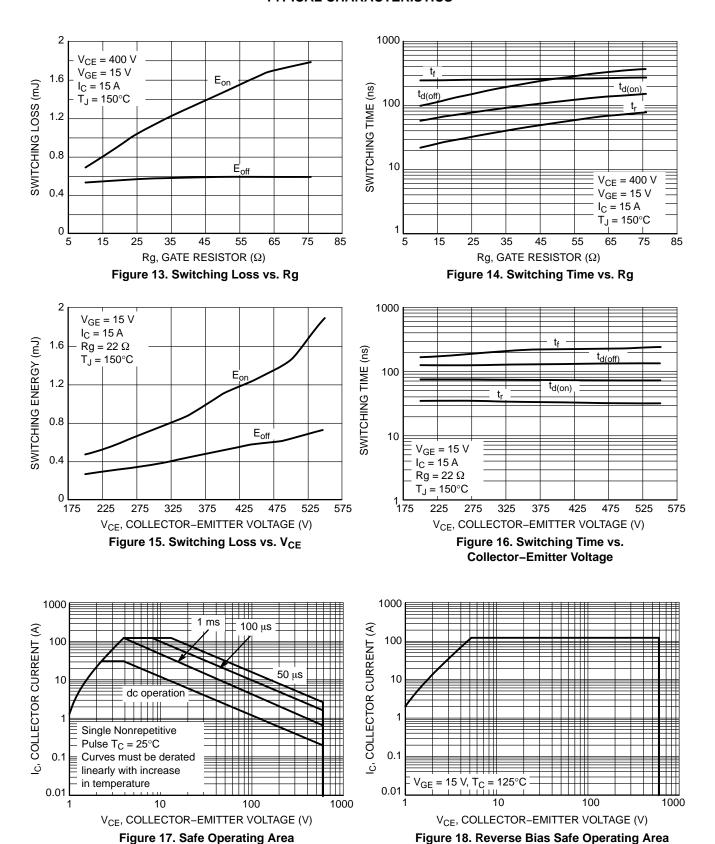


Figure 12. Switching Time vs. I_C

Figure 11. Switching Loss vs. I_C

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

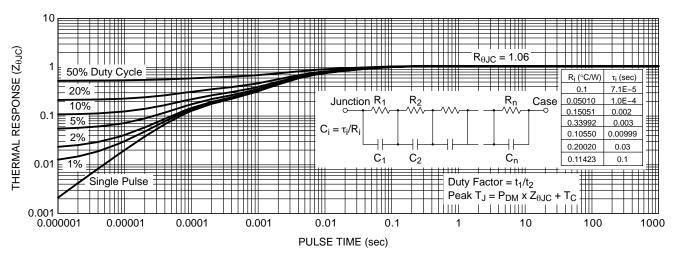


Figure 19. IGBT Transient Thermal Impedance

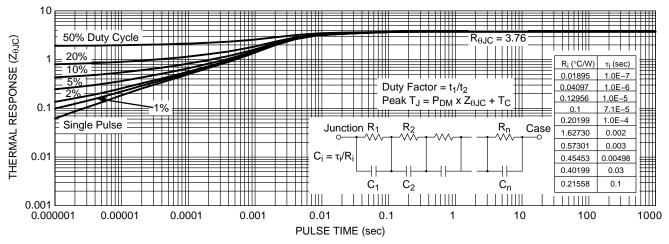


Figure 20. Diode Transient Thermal Impedance

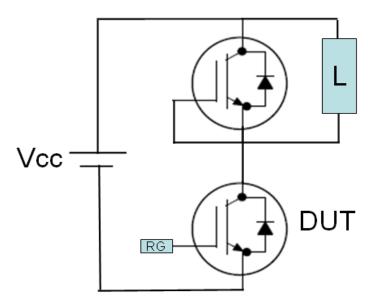


Figure 21. Test Circuit for Switching Characteristics

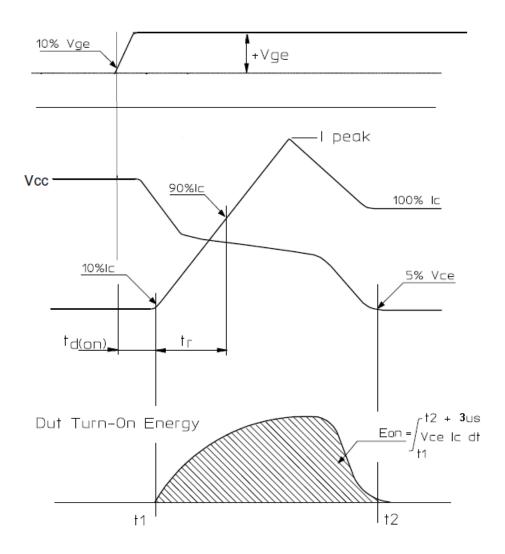


Figure 22. Definition of Turn On Waveform

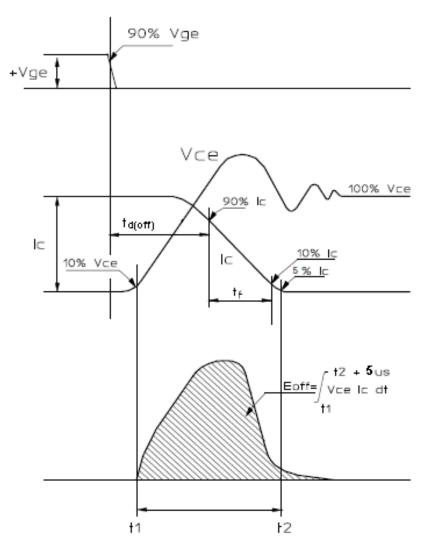
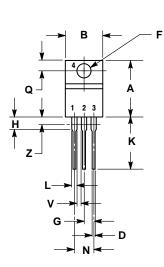
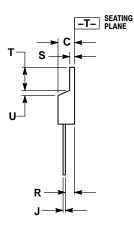


Figure 23. Definition of Turn Off Waveform

PACKAGE DIMENSIONS

TO-220 CASE 221A-09 **ISSUE AH**





- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.415	9.66	10.53
C	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

STYLE 9:

- PIN 1. GATE
 - 2. COLLECTOR
 - **EMITTER**
 - COLLECTOR

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